



The 7th IEEE Asia Workshop on Wide-Band-Gap Power Devices & Applications

Aug. 22-25, 2027 – Kyoto, Japan

<http://wipda-asia2027.org/>

Call for Papers

WiPDA-Asia 2027 invites abstract submissions on original work in wide bandgap power *devices*, their *packaging* and their *applications*. Accepted papers will be presented orally or as posters and the final manuscripts will be submitted to IEEE Xplore. Keynote talks by academic and industrial leading experts worldwide will discuss technology development trends. Tutorials covering all three topics will be offered on the first day. A number of booths will be available for exhibition.

Topics of interest

- Device structures and fabrication techniques
- Device characterization and modelling
- Advanced packaging solutions
- Robustness and reliability studies
- Novel and advanced applications (Transportation, Data-Centres, SSTs)
- Ultra Wide-Band-Gap materials
- Gate-drivers and auxiliary circuits
- High-efficiency high power-density converters
- AI and machine learning for WBG devices, packaging and converters

Key Dates

Abstract submission:
Nov. 15th, 2026

Review notification:
Jan. 10th, 2027

Final paper submission:
Feb. 12th, 2027

Organising Committee

General Chairs

Alberto Castellazzi
KUAS, Japan

Co-Chair

Katsuaki Saito
Nexperia Japan

Keynotes Chair

Marina Antoniou
Warwick University, UK

TPC Chairs

Keiji Wada
Tokyo Metropolitan University, Japan

Co-chairs

Chih-Fang Huang (Devices)
National Tsing-Hua University, Taiwan

Yoshinari Ikeda (Packaging)
Fuji Electric/Tohoku University, Japan

Michael Hartmann (Applications)
Graz University of Technology, Austria

Tutorials Chair

Keisuke Wakamoto
ROHM Semiconductor, Japan

Website and Publications Chairs

Michihiro Shintani, Hajime Takayama
Kyoto Institute of Technology, Japan

Local Organization

Ryo Takahashi, Fuat Kucuk, Ahmed Ibrahim
KUAS, Japan

Industry Liaison

Tsuyoshi Funaki
Osaka University, Japan



**IEEE POWER
ELECTRONICS SOCIETY**
Powering a Sustainable Future

